PCN# : P1BCA
Issue Date : Nov. 30, 2011

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Feb. 28, 2012

Expected First Date Code of Changed Product :1209

Last Date for Shipment of Unchanged Product : Feb. 28, 2012

Description of Change (From) :

Products assembled in the 4 pin black opto coupler package at the current manufacturing site in Thailand

Description of Change (To) :

Products assembled in the 4 pin black opto coupler package at new manufacturing site in China.

Reason for Change:

The alternate facility in China is being added as an assembly and test site for Fairchild opto coupler products assembled in the 4 pin black opto coupler package. This facility has successfully manufactured opto coupler products for many years, including the assembly and test of the 4 pin black package. The products affected by this PCN will use the same build of materials (BOM) as are used for the 4 pin black assembly at the current manufacturing site in Thailand. There will be no changes to form, fit or function.

Affected Product(s):

FOD617A3SD	FOD617B	FOD617B3SD
FOD617C	FOD617C3SD	FOD814
FOD814300	FOD814300W	FOD8143S
FOD8143SD	FOD814A	FOD814A300
FOD814A300W	FOD814A3S	FOD814A3SD
FOD814AS	FOD814ASD	FOD814S
FOD814SD	FOD817	FOD817300
FOD817300W	FOD8173S	FOD8173SD
FOD817A	FOD817A300	FOD817A300W
FOD817A3S	FOD817A3SD	FOD817AS
FOD817ASD	FOD817B	FOD817B300
FOD817B300W	FOD817B3S	FOD817B3SD
FOD817BS	FOD817BSD	FOD817C
FOD817C300	FOD817C300W	FOD817C3S
FOD817C3SD	FOD817CS	FOD817CSD
FOD817D	FOD817D300	FOD817D300W
FOD817D3S	FOD817D3SD	FOD817DS
FOD817DSD	FOD817S	FOD817SD
FOD817X_5700W	FOD817X_5701W	FOD817X_5711
FOD852	FOD852300	FOD852300W
FOD8523S	FOD8523SD	FOD852S
FOD852SD		

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
Q20110586	FOD817	4PB	N/A	6

Test Description:	**Condition:**	**Standard :**	**Duration:**	**Results:**
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/1080
Autoclave	121C, 100%RH	JESD22-A102	168 hrs	0/270
Bond Pull		JESD22-C100		0/120
Bond Shear		AEC-Q100-001		0/120
Die Shear		MIL-STD-883-2019		0/120
High Humidity, High Temp, Rev. Bias	85C, 85%RH, 64V	JESD22-A101B	1000 hrs	0/270
High Temperature Op Life Test	110C		1000 hrs	0/270
High Temperature Reverse Bias	110C, 30V	JESD22-A108	1000 hrs	0/135
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/270
Low Temperature Storage	-55C		1000 hrs	0/270
Power Cycle	Delta 100CC, 2 Min cycle	MIL-STD-750-1036	15000 cycle	0/90
Solder Dip	260C, 10 sec	JESD22-B106		0/135
Room Temperature Op Life	25C		1000 hrs	0/135
Condtion C Steam Aging (8 hr), Condition B Solder Dip (245C, 5 sec) (Solderability)		JESD22-B102		0/135
Custom Temp Cycle (Temperature Cycle)	-55C, 125C	JESD22-A104	1000 hrs	0/270